



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et al.

Serial No.: 09/917,127

Filed: July 27, 2001

For: METHOD FOR FABRICATING A
CHIP SCALE PACKAGE USING WAFER
LEVEL PROCESSING AND DEVICES
RESULTING THEREFROM

Confirmation No.: 3326

Examiner: M. Trinh

Group Art Unit: 2822

Attorney Docket No.: 2269-3572.1US
(97-1243.01/US)

Notice of Allowance Mailed:

January 26, 2004

Express Mail Mailing Label No.: EV 325782292 US

Date of Deposit with USPS: April 14, 2004

Person making Deposit: Christopher Haughton

TRANSMITTAL LETTER

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

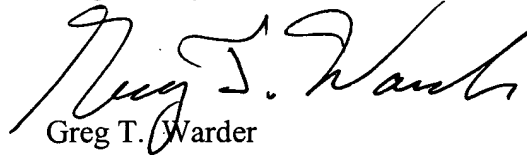
Applicants submit herewith Part B - Fee(s) Transmittal for the above-captioned application and a check in the amount of \$1,645.00 in payment therefor plus five (5) copies of the patent when issued.

Serial No.: 09/917,127

Also, enclosed is an Amendment Pursuant to 37 C.F.R. § 1.312(a) (3 pages); Comments on Statement of Reasons for Allowance (3 pages); and Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages).

Applicants understand that no additional fees are required. However, if the Office determines that any comparison fees or other additional fees are required, the Commissioner is authorized to charge any such fees to TraskBritt Deposit Account No. 20-1469. A copy of this Transmittal Letter is enclosed for deposit account charging purposes.

Respectfully submitted,



Greg T. Warder

Registration No. 50,208

Attorney for Applicant(s)

TRASKBRITT

P.O. Box 2550

Salt Lake City, Utah 84110-2550

Telephone: 801-532-1922

Date: April 14, 2004

GTW/ps:ljb

Enclosures: Part B - Issue Fee Transmittal

Check No. 20152 in the amount of \$1,645.00

Copy of Transmittal Letter

Amendment Pursuant to 37 C.F.R. § 1.312(a) (3 pages)

Comments on Statement of Reasons for Allowance (3 pages)

Fee Addressee for Receipt of PTO Notices Relating to Maintenance Fees (2 pages)



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COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This communication is filed in response to the Notice of Allowability mailed January 26, 2004. The purpose of this communication is to set forth Applicant's comments, pursuant to 37 C.F.R. §1.104(e), on the Examiner's Statement of Reasons for Allowance accompanying the Notice of Allowability.

The Examiner has indicated:

Applicant's amendment and convincing remarks of record have overcome the rejections of record. The references including Uemura (6,331,450) of record, alone or in combination, do not anticipatively disclose each and every aspect of the claimed method, or fairly make a prima facie obvious case of the claimed method, in combination with other processing claimed limitations as recited in base claim 1, the inclusion of forming a pattern of mutually traverse channels in the active surface to a depth below the at least one layer of integrated circuitry, the channels circumscribing a semiconductor element location comprised of at least one individual die and exposing peripheral edges of the at least one layer of integrated circuitry; and forming a layer of encapsulant materials over substantially all of the active surface and into the channels such that a surface of the layer of encapsulant material has a pattern of depressions over the channels and a portion of the at least one intermediate conductive element is exposed through and coplanar with the surface of the layer of encapsulant material.

Applicants concur with the reasons as stated by the Examiner insofar as they comprise a summary, and are exemplary and not limiting. However, the scope of the claims is based on the actual language of the claims and equivalents thereof, and not on a paraphrase or summary of the claim language. Independent claim 1 recites features and methodology in addition to those described in the Statement of Reasons for Allowance. Furthermore, dependent claims 2 through 4, 6, 11 through 18 and 21 through 25 recite elements in addition to those of the independent claims and which are also not reflected in the Statement of Reasons for Allowance. Such additional features and elements, in combination with those of the independent claims from which each claim depends, provide additional reasons for patentability in accordance with the literal language thereof and all equivalents.

Therefore, to the extent that the Examiner's reasons for allowance as stated are not relevant to, or wholly encompassing of, a particular claim, independent or dependent, Applicants assume that (pursuant to 37 C.F.R. § 1.104(e)) the Examiner has determined that the record of the prosecution as a whole of the application makes clear the reasons for allowing those claims.

Further, it appears, pursuant to M.P.E.P. 1302.14, that the Examiner's statement of reasons for allowance is not intended to encompass all of the reasons for allowance.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Greg T. Warder", written in a cursive style.

Greg T. Warder

Registration No. 50,208

Attorney for Applicant(s)

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P.O. Box 2550

Salt Lake City, Utah 84110-2550

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Document in ProLaw